



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: David M. Curran, et al.

Serial No: 10/029,788

Examiner: Timothy V. Eley

Filed: 10/26/2001

For: METHOD FOR REDUCING THE THICKNESS OF SPIN-ON GLASS ON
SEMICONDUCTOR WAFERS

Docket No: TI-29038

Conf. No: 5683

Art Unit: 3724

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TECHNOLOGY CENTER R3700

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on 10-10-03.


Ann Trent

Dear Sir:

Responsive to the Office Action mailed July 14, 2003, in connection with the above identified application, Applicants respectfully submit the following amendments and remarks.